Notification about the transfer of the semiconductor business

The semiconductor business of Panasonic Corporation was transferred on September 1, 2020 to Nuvoton Technology Corporation (hereinafter referred to as "Nuvoton"). Accordingly, Panasonic Semiconductor Solutions Co., Ltd. became under the umbrella of the Nuvoton Group, with the new name of Nuvoton Technology Corporation Japan (hereinafter referred to as "NTCJ").

In accordance with this transfer, semiconductor products will be handled as NTCJ-made products after September 1, 2020. However, such products will be continuously sold through Panasonic Corporation.

Publisher of this Document is NTCJ.

If you would find description "Panasonic" or "Panasonic semiconductor solutions", please replace it with NTCJ.

Except below description page
 "Request for your special attention and precautions in using the technical information and semiconductors described in this book"

Nuvoton Technology Corporation Japan

Doc No. TT4-EA-15019

Revision. 2

Panasonic

MOS FET FC8V22290L

FC8V22290L

Gate resistor installed Dual N-channel MOS FET For lithium-ion secondary battery protection circuits

■ Features

- Source-source ON Resistance:Rss(on) typ. = 11.5 m Ω (VGS = 4.5 V)
- · Built-in gate resistor
- Halogen-free / RoHS compliant (EU RoHS / UL-94 V-0 / MSL:Level 1 compliant)
- Marking Symbol: 4H

■ Packaging

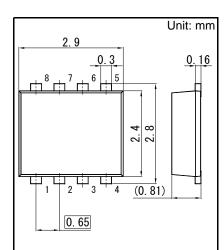
Embossed type (Thermo-compression sealing): 3 000 pcs / reel (standard)

■ Absolute Maximum Ratings Ta = 25 °C

Parameter		Symbol	Rating	Unit	
Drain-source Voltage		VDS	20	V	
Gate-source Voltage		VGS	±12	V	
Source Current	DC *1	IS1	7.5	Α	
	DC *2	IS2	11	Α	
	Pulse *3	ISp	75	Α	
Total Power Dissipation	Ta = 25 °C, DC *1	PD1	1.0	W	
	Ta = 25 °C, DC ^{*2}	PD2	2.0		
	Ta = 25 °C, t = 10 s *1	PD3	1.2		
Channel Temperature		Tch	150	°C	
Storage Temperature Range		Tstg	-55 to +150	°C	
Thermal Resistance (ch-a)		Rth(ch-a)	125	°C/W	

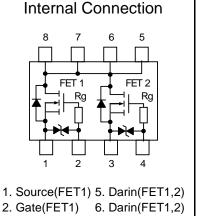
*1 Mounted on FR4 board ($25.4 \text{ mm} \times 25.4 \text{ mm} \times t0.8 \text{ mm}$) Note using the minimum recommended pad size (36µm Copper).

- *2 Mounted on Ceramic substrate (70 mm x 70 mm x t1.0 mm).
- *3 $t = 10 \mu s$, Duty Cycle $\leq 1 \%$



- 1. Source(FET1) 5. Darin(FET1,2)
- 2. Gate(FET1) 6. Darin(FET1,2)
- 3. Source(FET2) 7. Darin(FET1,2)
- 4. Gate(FET2) 8. Darin(FET1.2)

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Panasonic	WMini8-F1
JEITA	SC-115
Code	-



- 3. Source(FET2) 7. Darin(FET1,2)
- 4. Gate(FET2) 8. Darin(FET1,2)

MOS FET

FC8V22290L

Panasonic

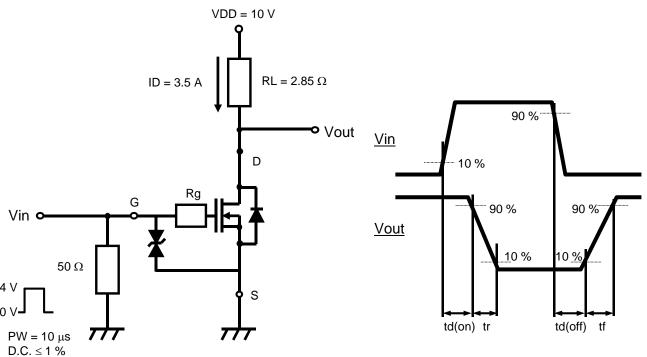
■ Electrical Characteristics Ta = 25 °C ± 3 °C

Parameter	Symbol	Conditions	Min	Тур	Max	Unit	
Drain-source Breakdown Voltage	VDSS	ID = 1 mA, VGS = 0 V	20			V	
Zero Gate Voltage Drain Current	IDSS	VDS = 20 V, VGS = 0 V			1.0	μΑ	
Gate-source Leakage Current	IGSS	$VGS = \pm 8 \text{ V}, VSS = 0 \text{ V}$			±1.0	μΑ	
Gate-source Threshold Voltage	Vth	ID = 0.44 mA, VDS = 10 V	0.35	0.9	1.4	V	
	RSS(on)1	IS = 3.5 A, VGS = 4.5 V	8.2	11.5	15.5	mΩ	
Source-source On-state Resistance		IS = 3.5 A, VGS = 3.8 V	8.5	12.5	16.5		
Source-source Oil-state Resistance	RSS(on)3	IS = 3.5 A, VGS = 3.1 V	9	13.5	22.5		
	RSS(on)4	IS = 3.5 A, VGS = 2.5 V	9.5	16.5	32.5		
Body Diode Forward Voltage	VSD	IF = 3.5 A, VGS = 0 V		0.8	1.2	V	
Input Capacitance *1	Ciss	VDS = 10 V, VGS = 0 V, f = 1 KHz		1250		pF	
Output Capacitance *1	Coss			140			
Reverse Transfer Capacitance *1	Crss			115			
Turn-on delay Time *1,*2	td(on)	VDD = 10 V, VGS = 0 to 4.0 V		0.25		0	
Rise Time *1,*2	tr	ID = 3.5 A		0.65		μS	
Turn-off delay Time *1,*2	td(off)	VDD = 10 V, VGS = 4.0 to 0 V		2.3		0	
Fall Time *1,*2	tf	ID = 3.5 A		1.4		μS	
Total Gate Charge *1	Qg	VDD = 10 V		10.5			
Gate-source Charge *1	Qgs	VGS = 0 to $4.0 V$,		4	nC		
Gate-drain Charge *1	Qgd	ID = 3.5 A		4			

Note Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 Measuring methods for transistors.

- *1 Guaranteed by design, not subject to production testing
- *2 Measurement circuit for Turn-on Delay Time / Rise Time / Turn-off Delay Time / Fall Time

Note2:Measurement circuit

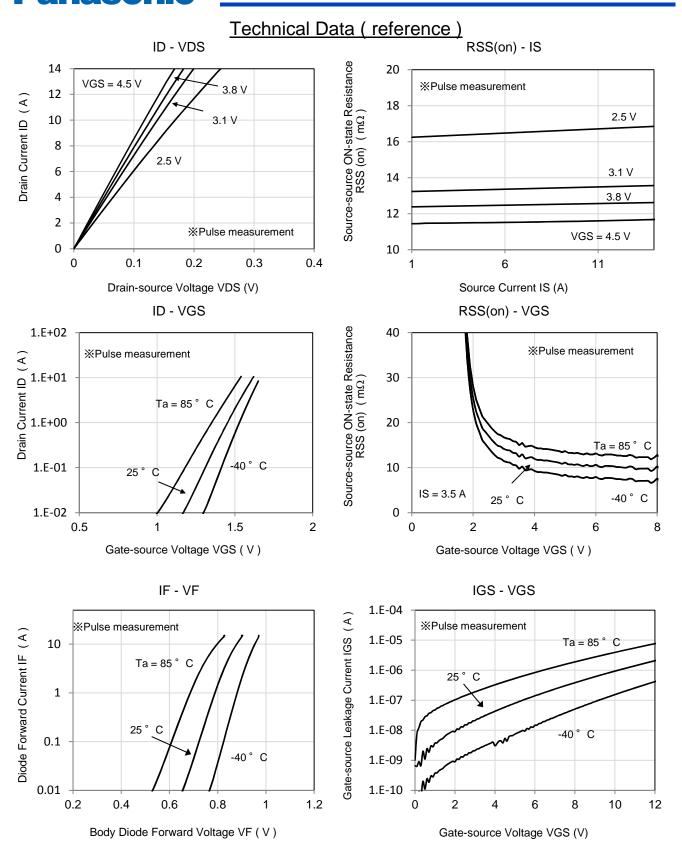


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Established: 2015-04-01 Revised: 2015-05-19 **Panasonic**

MOS FET

FC8V22290L

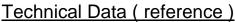


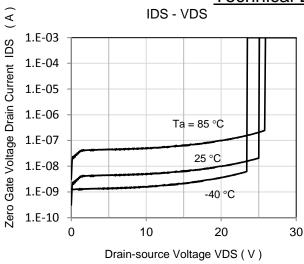
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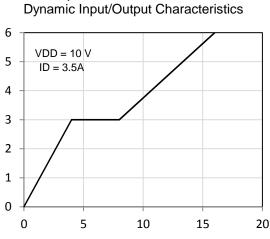
FC8V22290L

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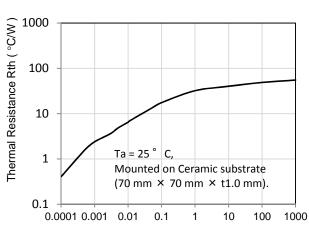
Gate - source Voltage VGS (V) 5 4 3

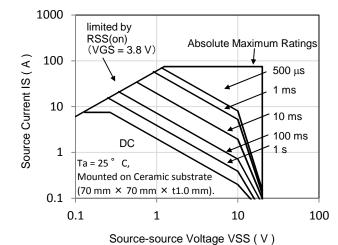


Rth - tsw

Safe Operating Area

Gate Charge (nC)





Pulse Width tsw (s)

Normalized Effective Transient Thermal Impedance Thermal Response 10 Duty Cycle = 0.5 0.05 0.02 0.1 Ta = 25° C, Mounted on Ceramic substrate $(70 \text{ mm} \times 70 \text{ mm} \times t1.0 \text{ mm})$ Single Pulse 0.0001 0.001 0.01 0.1 10 100 Square Wave Pulse Duration (s)

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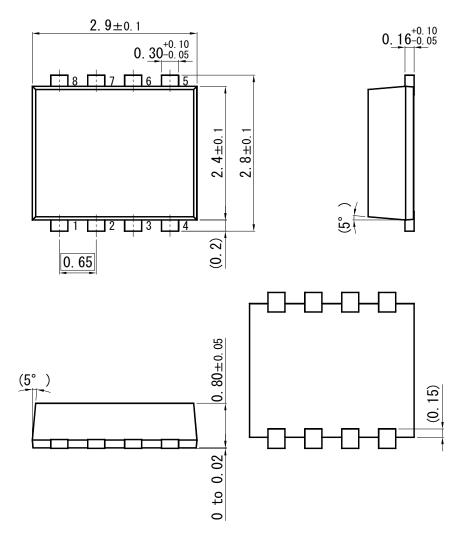
MOS FET

FC8V22290L

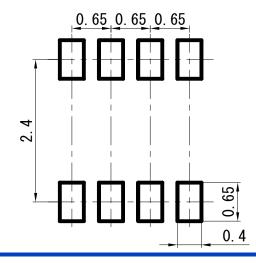
WMini8-F1

Panasonic

Unit: mm



■ Land Pattern (Reference) (Unit: mm)



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